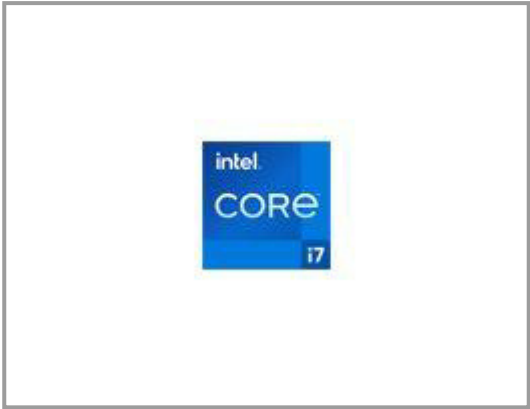


Intel Core i7 13700F - 2.1 GHz - 16 Kerne - 24 Threads

30 MB Cache-Speicher - FCLGA1700 Socket - OEM

Gruppe	Prozessoren
Hersteller	Intel
Hersteller Art. Nr.	CM8071504820806
EAN/UPC	8592978422349



Beschreibung

Intel Core i7 13700F - 2.1 GHz - 16 Kerne - 24 Threads - 30 MB Cache-Speicher - FCLGA1700 Socket - OEM

Hauptmerkmale

Produktbeschreibung	Intel Core i7 13700F / 2.1 GHz Prozessor - OEM
Produkttyp	Prozessor
Prozessortyp	Intel Core i7 13700F (13th Gen)
Anz. der Kerne	16 Kerne / 24 Threads
Cache-Speicher	30 MB
Geeignete Sockel	FCLGA1700 Socket
Prozessoranz.	1
Taktfrequenz	2.1 GHz (P-Kern) / 1.5 GHz (E-Kern)
Max. Turbo-Taktfrequenz	5.2 GHz (P-Kern) / 4.1 GHz (E-Kern)
Herstellungsprozess	10 nm

Funktionen	Enhanced SpeedStep technology, Hyper-Threading-Technologie, Unterstützung für Execute Disable Bit, Intel Virtualization Technology, Intel 64 Technology, Streaming-SIMD-Erweiterungen 4.1, Streaming-SIMD-Erweiterungen 4.2, Intel Turbo Boost Technology 2.0, Intel AES New Instructions (AES-NI), Thermal Monitoring Technologies, Intel Virtualization Technology for Directed I/O (VT-d), Idle States, Intel VT-x with Extended Page Tables (EPT), Intel Secure Key, Intel Advanced Vector Extensions 2 (AVX2.0), Intel OS Guard, Intel Turbo Boost Max Technology 3.0, Intel Speed Shift Technology, Intel Volume Management Device (VMD), Intel Boot Guard, Intel Deep Learning Boost (DL Boost), Intel Control-Flow Enforcement Technology, Intel Gaussian and Neural Accelerator 3.0, Intel Thread Director, Instruction Set 64-bit, Intel Standard Manageability (ISM), Mode-based Execute Control (MBEC)
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Ausführliche Details

	Allgemein
Produkttyp	Prozessor
	Prozessor
Typ / Formfaktor	Intel Core i7 13700F (13th Gen)
Anz. der Kerne	16 Kerne
Anz. der Threads	24 Threads
Cache-Speicher	30 MB
Cache-Speicher-Details	Smart Cache - 30 MB L2 - 24 MB
Prozessoranz.	1
Taktfrequenz	2.1 GHz (P-Kern) / 1.5 GHz (E-Kern)
Max. Turbo-Taktfrequenz	5.2 GHz (P-Kern) / 4.1 GHz (E-Kern)
Geeignete Sockel	FCLGA1700 Socket
Herstellungsprozess	10 nm
Thermal Design Power (TDP)	219 W
Temperaturspezifikationen	100 °C
PCI Express Revision	4.0/5.0
PCI Express-Konfigurationen	1x16+4, 2x8+4

Architektur-Merkmale	Enhanced SpeedStep technology, Hyper-Threading-Technologie, Unterstützung für Execute Disable Bit, Intel Virtualization Technology, Intel 64 Technology, Streaming-SIMD-Erweiterungen 4.1, Streaming-SIMD-Erweiterungen 4.2, Intel Turbo Boost Technology 2.0, Intel AES New Instructions (AES-NI), Thermal Monitoring Technologies, Intel Virtualization Technology for Directed I/O (VT-d), Idle States, Intel VT-x with Extended Page Tables (EPT), Intel Secure Key, Intel Advanced Vector Extensions 2 (AVX2.0), Intel OS Guard, Intel Turbo Boost Max Technology 3.0, Intel Speed Shift Technology, Intel Volume Management Device (VMD), Intel Boot Guard, Intel Deep Learning Boost (DL Boost), Intel Control-Flow Enforcement Technology, Intel Gaussian and Neural Accelerator 3.0, Intel Thread Director, Instruction Set 64-bit, Intel Standard Manageability (ISM), Mode-based Execute Control (MBEC)
	Verschiedenes
Verpackung	OEM/Tray
	Herstellergarantie
Service und Support	Begrenzte Garantie - 1 Jahr

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